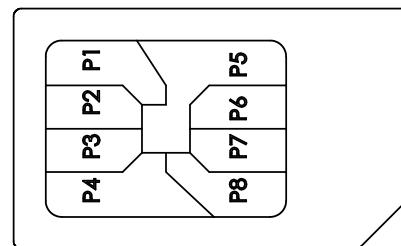


RECOMMENDED P.C.B.LAYOUT
TOLERANCE: ±0.05mm



- P1 : VCC
- P2 : RST
- P3 : CLK
- P4 : RESERVED
- P5 : GND
- P6 : VPP
- P7 : I / O
- P8 : RESERVED

NOTES:
1.MATERIAL:
HOUSING: HI-TEMP. PLASTIC,BLACK,UL 94V-0
CONTACT: COPPER ALLOY,T=0.15mm.
SHEEL A: COPPER ALLOY,T=0.15mm.
SHEEL B: STAINLESS STEEL,T=0.15mm.
LOCK: STAINLESS STEEL,T=0.15mm.

2.FINISH:
CONTACT: 50u" MIN Ni UNDERPLATING OVERALL.
GOLD FLASH OVER PLATING ON CONTACT AND SLODER AREA.
SHELL A: 50u" MIN Ni UNDERPLATING OVERALL,
TIN PLATING ON CONTACT AND SLODER AREA.

3.ALL DIMENSIONS MARKED ▼ MUST BE CONTROLLED BY QC.

PIN No.	DESCPTION	PIN No.	DESCPTION
SIM CARD A PIN 1	GND	SIM CARD A PIN 1	GND
SIM CARD A PIN 2	VCC	SIM CARD A PIN 2	VCC
SIM CARD A PIN 3	VPP	SIM CARD A PIN 3	VPP
SIM CARD A PIN 4	RST	SIM CARD A PIN 4	RST
SIM CARD A PIN 5	I/O	SIM CARD A PIN 5	I/O
SIM CARD A PIN 6	CLK	SIM CARD A PIN 6	CLK

REV.	ECN NO.	DESCRIPTION	DATE	UNITS: mm	GENERAL TOLERANCE	DRAW:	PART NO:
		INITIAL RELEASE	23/09/2011	DATE: 23/9/2011	X. ±0.30 .X ±0.20 .XX ±0.10 .XXX ±0.05	SEE NOTE	S18-2B0646FA
				SCALE: 3 / 1	X." ±2.00" .X" ±1.00" .XX" ±0.50" .XXX" ±0.10"	CHECKED:	TITLE: 横插双层 SIM CARD 垫高型 H4.6
				SHEET: 1 / 1	MATERIAL: SEE NOTE	APPROVE:	DRAWING NO:
				REV. A	FINISH: SEE NOTE		



鸿日达电子科技有限公司
HONGRIDA ELECTRONIC TECHNOLOGY CO.,LTD.